

# SN74LV20A Dual 4-Input Positive-NAND Gate

## 1 Features

- Operation of 2V to 5.5V  $V_{CC}$
- Max  $t_{pd}$  of 6ns at 5V
- Typical  $V_{OLP}$  (output ground bounce) < 0.8V at  $V_{CC}$  = 3.3V,  $T_A$  = 25°C
- Typical  $V_{OHV}$  (output  $V_{OH}$  undershoot) > 2.3V at  $V_{CC}$  = 3.3V,  $T_A$  = 25°C
- $I_{off}$  supports partial-power-down mode operation
- Latch-up performance exceeds 100mA per JESD 78, Class II

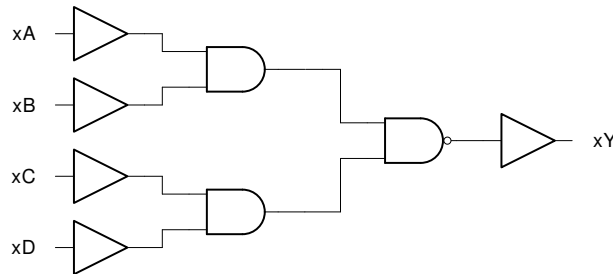
## 2 Description

These dual 4-input positive-NAND gates are designed for 2V to 5.5V  $V_{CC}$  operation.

### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>	BODY SIZE <sup>(3)</sup>
SN74LV20A	DGV (TVSOP, 14)	3.60mm x 6.4mm	3.60mm x 4.4mm
	D (SOIC, 14)	8.65mm x 6mm	8.65mm x 3.9mm
	NS (SOP, 14)	10.20mm x 7.8mm	10.3mm x 5.3mm
	DB (SSOP, 14)	6.20mm x 7.8mm	6.20mm x 5.3mm
	PW (TSSOP, 14)	5.00mm x 6.4mm	5.00mm x 4.4mm

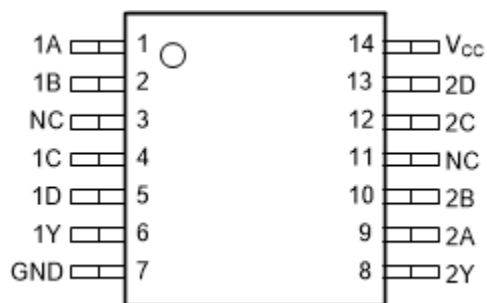
- (1) For more information, see [Section 10](#).
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.
- (3) The body size (length × width) is a nominal value and does not include pins.



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## 3 Pin Configuration and Functions



**Figure 3-1. SN74LV20A D, DB, DGV, NS, or PW Package; 14-Pin SOIC, SSOP, TVSOP, SOP, or TSSOP (Top View)**

**Table 3-1. Pin Functions**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
1A	1	I	1A Input
1B	2	I	1B Input
NC	3	—	Not internally connected
1C	4	I	1C Input
1D	5	I	1D Input
1Y	6	O	1Y Output
2Y	8	O	2Y Output
2A	9	I	2A Input
2B	10	I	2B Input
NC	11	—	Not internally connected
2C	12	I	2C Input
2D	13	I	2D Input
GND	7	—	Ground Pin
V <sub>CC</sub>	14	—	Power Pin

(1) Signal Types: I = Input, O = Output.

## 4 Specifications

### 4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	−0.5	7	V
$V_I$	Input voltage range <sup>(2)</sup>	−0.5	7	V
$V_O$	Output voltage range applied in high or low state <sup>(2) (3)</sup>	−0.5	$V_{CC} + 0.5$	V
$V_O$	Output voltage range applied in power-off state <sup>(2)</sup>	−0.5	7	V
$I_{IK}$	Input clamp current	$(V_I < 0)$		−20 mA
$I_{OK}$	Output clamp current	$(V_O < 0)$		−50 mA
$I_O$	Continuous output current	$(V_O = 0 \text{ to } V_{CC})$		±25 mA
	Continuous current through $V_{CC}$ or GND			±50 mA
$T_J$	Junction Temperature			150 °C
$T_{stg}$	Storage temperature	−65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.

### 4.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000
		Charged device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000
			V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 4.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	2	5.5	V
$V_{IH}$	High level input voltage	$V_{CC} = 2 \text{ V}$	1.5	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	$V_{CC} \times 0.7$	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.7$	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$	
$V_{IL}$	Low level input voltage	$V_{CC} = 2 \text{ V}$	0.5	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	$V_{CC} \times 0.3$	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.3$	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.3$	
$V_I$	Input voltage	0	5.5	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High level output current	$V_{CC} = 2 \text{ V}$	−50	μA
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	−2	mA
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	−6	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	−12	

### 4.3 Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$I_{OL}$	$V_{CC} = 2\text{ V}$		50	$\mu\text{A}$
	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		2	mA
	$V_{CC} = 3\text{ V to }3.6\text{ V}$		6	
	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		12	
$\Delta t/\Delta v$	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		200	ns/V
	$V_{CC} = 3\text{ V to }3.6\text{ V}$		100	
	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		20	
$T_A$	Operating free-air temperature	–40	85	$^{\circ}\text{C}$

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#)

### 4.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74LV20A					UNIT
	D	DB	DGV	NS	PW	
	14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance					$^{\circ}\text{C/W}$
	86	96	127	76	113	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report ([SPRA953](#)).

### 4.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}$	MIN	TYP	MAX	UNIT
$V_{OH}$	$I_{OH} = -50\text{ }\mu\text{A}$	2 V to 5.5 V	$V_{CC} - 0.1$			V
	$I_{OH} = -2\text{ mA}$	2.3 V	2			
	$I_{OH} = -6\text{ mA}$	3 V	2.48			
	$I_{OH} = -12\text{ mA}$	4.5 V	3.8			
$V_{OL}$	$I_{OL} = 50\text{ }\mu\text{A}$	2 V to 5.5 V			0.1	V
	$I_{OL} = 2\text{ mA}$	2.3 V			0.4	
	$I_{OL} = 6\text{ mA}$	3 V			0.44	
	$I_{OL} = 12\text{ mA}$	4.5 V			0.55	
$I_I$	Input leakage current	$V_I = 5.5\text{ V or GND}$	0 to 5.5 V		$\pm 1$	$\mu\text{A}$
$I_{CC}$	Supply current	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		20	$\mu\text{A}$
$I_{off}$	Off-state leakage current	$V_I$ or $V_O = 0$ to 5.5 V	0 V		5	$\mu\text{A}$
$C_i$	Input capacitance	$V_I = V_{CC}$ or GND	3.3 V	1.9		pF

### 4.6 Switching Characteristics, $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^{\circ}\text{C}$			SN74LV20A		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A, B, C or D	Y	$C_L = 15\text{ pF}$		6.8	11.6	1	13.5	ns
$t_{pd}$	A, B, C or D	Y	$C_L = 50\text{ pF}$		9.2	15.3	1	18.5	

#### 4.7 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#) )

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN74LV20A		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A, B, C, or D	Y	$C_L = 15\text{ pF}$		4.9	6.6	1	8	ns
$t_{pd}$	A, B, C, or D	Y	$C_L = 50\text{ pF}$		6.5	10.1	1	11.5	

#### 4.8 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#) )

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN74LV20A		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A, B, C, or D	Y	$C_L = 15\text{ pF}$		3.7	5	1	6	ns
$t_{pd}$	A, B, C, or D	Y	$C_L = 50\text{ pF}$		4.8	7	1	8	

#### 4.9 Noise Characteristics

$V_{CC} = 3.3\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER <sup>(1)</sup>		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$		0.2	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$		0	−0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic $V_{OH}$		3.2		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

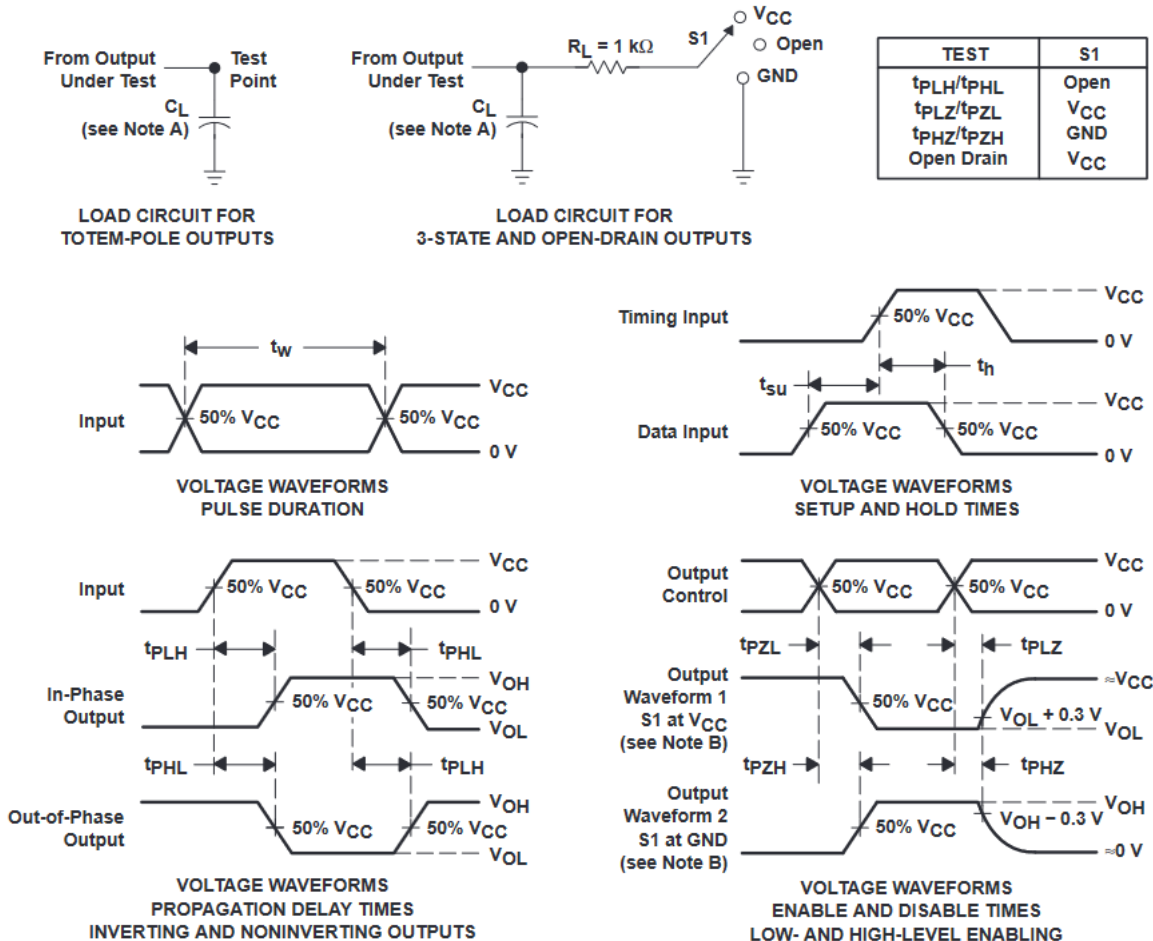
(1) Characteristics are for surface-mount packages only.

#### 4.10 Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		$V_{CC}$	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 10\text{ MHz}$		3.3 V	20.5	pF
				5 V	23.9	

## 5 Parameter Measurement Information



**Figure 5-1. Load Circuit and Voltage Waveforms**

- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
- D. The outputs are measured one at a time, with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

## 6 Detailed Description

### 6.1 Overview

The SN74LV20A devices perform the Boolean function  $Y = \overline{A \cdot B \cdot C \cdot D}$  or  $Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}$  in positive logic.

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

### 6.2 Functional Block Diagram

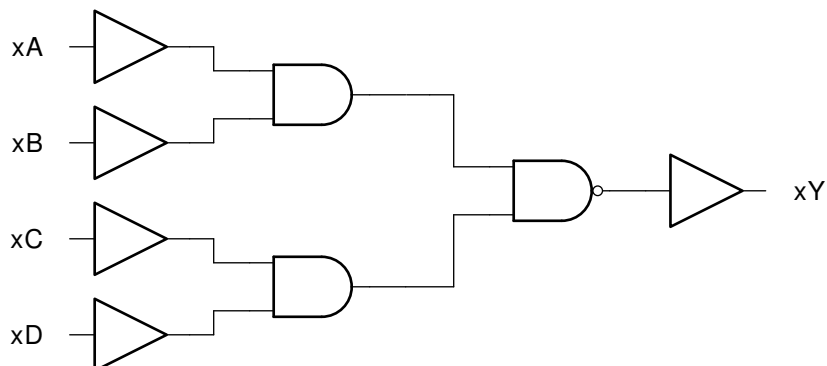


Figure 6-1. logic diagram (positive logic)

### 6.3 Device Functional Modes

Function Table  
(each gate)

INPUTS				OUTPUT Y
A	B	C	D	
H	H	H	H	L
L	X	X	X	H
X	L	X	X	H
X	X	L	X	H
X	X	X	L	H



## 7 Application and Implementation

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### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

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### 7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- $\mu$ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

### 7.2 Layout

#### 7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

## 8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 8.1 Documentation Support (Analog)

#### 8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LV20A	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 8.3 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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### 8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 8.6 Glossary

#### TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

## 9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision E (April 2005) to Revision F (May 2024)	Page
• Added <i>Package Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74LV20AD</a>	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-40 to 85	LV20A
<a href="#">SN74LV20ADBR</a>	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV20A
SN74LV20ADBR.A	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV20A
<a href="#">SN74LV20ADGVR</a>	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV20A
SN74LV20ADGVR.A	Active	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV20A
<a href="#">SN74LV20ADR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV20A
SN74LV20ADR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV20A
<a href="#">SN74LV20ANSR</a>	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV20A
SN74LV20ANSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV20A
<a href="#">SN74LV20APW</a>	Obsolete	Production	TSSOP (PW)   14	-	-	Call TI	Call TI	-40 to 85	LV20A
<a href="#">SN74LV20APWR</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	LV20A
SN74LV20APWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV20A
<a href="#">SN74LV20APWRG4</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV20A

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV20ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV20ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV20ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV20ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV20APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV20APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV20ADBR	SSOP	DB	14	2000	353.0	353.0	32.0
SN74LV20ADGVR	TVSOP	DGV	14	2000	353.0	353.0	32.0
SN74LV20ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LV20ANSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74LV20APWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74LV20APWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0



# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



## EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220762/A 05/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

**PW0014A**

## PACKAGE OUTLINE

**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

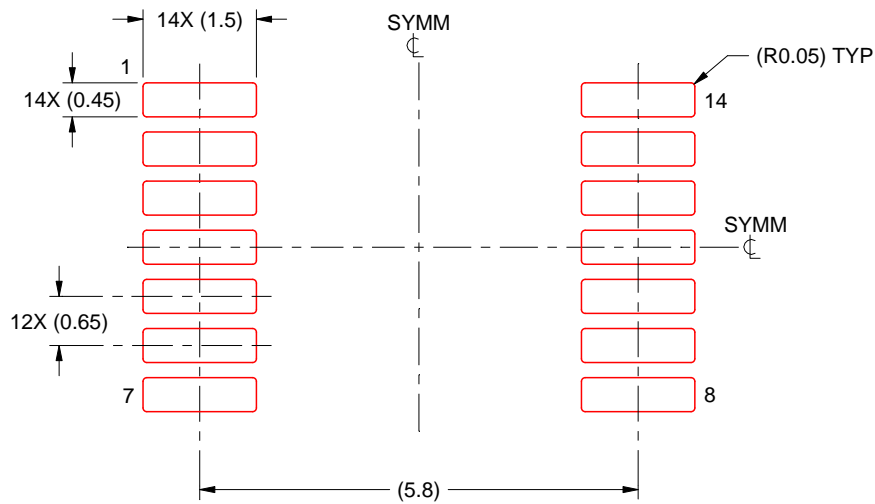


# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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